

ABSTRACT OF THE DISCLOSURE

Disclosed is an apparatus for preparing and supplying a slurry to a chemical mechanical polishing machine. The slurry contains liquid components at a predetermined mixing ratio. The apparatus includes draw ports for separately drawing therethrough the liquid components, and a discharge port for supplying the slurry to the machine. Feed pumps are arranged on feed lines for the liquid components, respectively, said feed lines extending from the individual draw ports to the discharge port, such that the feed pumps can draw the corresponding liquid components in specific amounts to give the mixing ratio and can deliver the thus-drawn liquid components toward the discharge port, respectively. Dampers and pressurization valves are arranged in combinations on the respective feed lines on delivery sides of the feed pumps. Flowmeters are arranged on downstream sides of the corresponding combinations of the dampers and pressurization valves. The apparatus is also provided with a programmable logic controller for controlling delivery rates of the individual feed pumps by using measurement values from the flowmeters. A slurry preparing and supplying method making use of a plurality of such apparatuses is also disclosed.